ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and Pa	IPC. Bannockł	ourn. Illinois. A	ll rights reserved ur ntions.	nder both	This docume level parts, t	ent is a declaration en	n of the substan compasses all lo	ces within the manufactur ower level materials for w	rer listed it hich the m	em. Note: if anufacturer	f the item is an as has engineering	sembly with low responsibility.	
				Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials an				ials and M	and Mfg Information			
Supplier Information													
Company name* Comp			Company unique ID			Unique ID Authority				Response Date*			
onsemi									2025-05-14				
Contact Name Title - Contact			et	Phor		Phone - Contact	Phone - Contact*			Email - Contact*			
Product-Env-Stewards Product Env			Enviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repre			presentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Prod			Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Item Num		Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	NCV752	NCV7520FPR2G Automotive Dr		er		2025-05-14		PH1		31.7	mg	Each	
Aanufacturing Proccess Inform	ation		·			·							
Terminal Plating / Grid Array Material Terminal Base Alloy		Alloy J-	-STD-020 MSL	Rating	Peak Proce	ss Body Temper	ature Max Time at Peak	Temperat	ure Numb	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy 3					260	C	30	secon	ds 3				
omments													
ITENTION: MSL 3 Rated item requir	es Bake and D	Dry Pack (after	electrical test)										
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl ohthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

select a RoHS exemption, if applied	cable [E] enter the weigh	, Requester or Supplier) [B at of the substance or the P	[] select the substa PM concentration	ance category (JIG or Requester) or enter [F] Optionally enter the positive (+) and	a value (Supplier). [C] selec negative (-) tolerance in per	t the substance (JI cent (Note: percer	G) or enter the substa t tolerance values are	nce and CAS (Other). [D] expected to cover a 3
sigma range of distribution unless Homogeneous Material	otherwise noted).	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	7.0		Supplier	Silicon (Si)	7440-21-3	Exempt		
Die Attach	0.3	mg mg	Supplier	Epoxy resin	proprietary data		0.033	mg mg
			Supplier	Copper(II) Oxide (CuO)	1317-38-0		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.24	mg
			Supplier	Oxirane	39817-09-9		0.024	mg
Lead Frame	31.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0382	mg
			Supplier	Iron (Fe)	7439-89-6		0.7473	mg
			Supplier	Copper (Cu)	7440-50-8		31.005	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0095	mg
Lead Frame plating	0.3	mg	Supplier	Silver (Ag)	7440-22-4		0.3	mg
Mold Compound-Black	38.2	mg		Epoxy resin	proprietary data		2.865	mg
			Supplier	Phenolic Resin	Proprietary Data		0.955	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.865	mg
			Supplier	Carbon Black (C)	1333-86-4		0.191	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.324	mg
Plating	3.8	mg	Supplier	Tin (Sn)	7440-31-5		3.8	mg
Wire Bond - Au	0.3	mg	Supplier	Gold (Au)	7440-57-5		0.3	mg